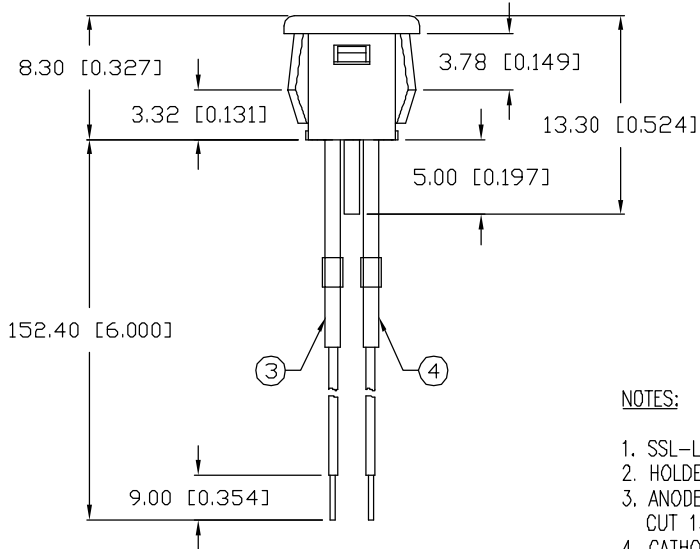
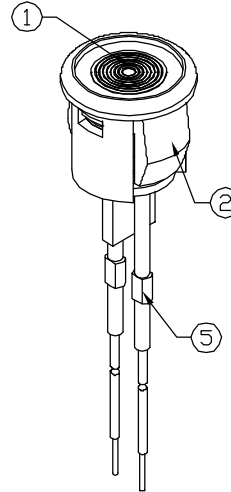
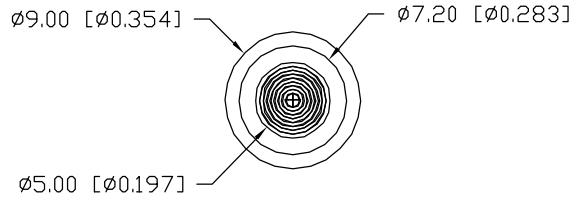


UNCONTROLLED DOCUMENT

PART NUMBER
SSI-LXH387ID-150

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	8.2.01



NOTES:

1. SSL-LX433ID LED.
2. HOLDER: LXP-SSI-387BSH, LXP-SSI-387BZL.
3. ANODE LEAD: LXP-WST24RTOC STRANDED, CUT 135mm, STRIP 4mm & 9mm.
4. CATHODE LEAD: LXP-WST24BLTOC STRANDED, CUT 135mm, STRIP 4mm & 9mm.
5. CRIMP LEADS EXTERNAL TO HOUSING. HEAT SHRINK OVER CRIMP-2 PLS.
6. PANEL HOLE CUT OUT: 5/16" DIAMETER.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		10		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

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REV. PART NUMBER
A SSI-LXH387ID-150

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T-5 FRESNEL LENS PANEL INDICATOR,
635nm HIGH INTENSITY RED LED, RED DIFFUSED LENS,
WITH 6" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 2.8.93
			PAGE: 1 OF 1
			SCALE: N/A